



Advances in High Precision Laser Micromachining

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Outline

- Introduction to Oxford Lasers
- Effect of wavelength & Pulse duration
- Process is the KEY!
- Examples of ns, ps and fs second micromachining
- Summary



- Didcot, Oxon (UK), Boston (USA), Paris (France)
- Founded in 1977 (Excimer and Copper Laser Manufacturer)

Oxford University spinout

- Two divisions: (a) Laser micromachining
(b) High-speed imaging
- Markets: microelectronics, solar, healthcare, automotive, biomedical, telecoms, R&D etc

We offer:

- **Turn-key Laser Micromachining Systems**
- **Sub-contract Laser Micromachining Service**
 - **Proof-of-Concept Trials**
 - **Contract R&D**
 - **Small and medium volume production**





Oxford Laser Range of Systems



Robust Full production System

C Series

**Advanced R&D System
Compact Micro-Machining System**

Alpha Series

Ultra Compact Micro-Machining System

J Series

Ultra fast System

Oxford Lasers' Workstation



Configurations can include:

- Different lasers (ns, ps, fs, IR, green, UV)
- Different motion control
- Beam conditioning
- Camera systems
- Auto Align
- Auto Focus
- Power measurement
- Cimita Software
- Part handling/automation

Importance of wavelength

The laser wavelength and material optical properties determine **light absorption** (i.e. the extent to which the material takes up the deposited energy)

Incident laser light on surface = [reflected] + [absorbed] + [transmitted]

Only **[absorbed]** light in the material is useful for *Laser Micromachining* and the optical penetration (absorption) depth defines the process resolution

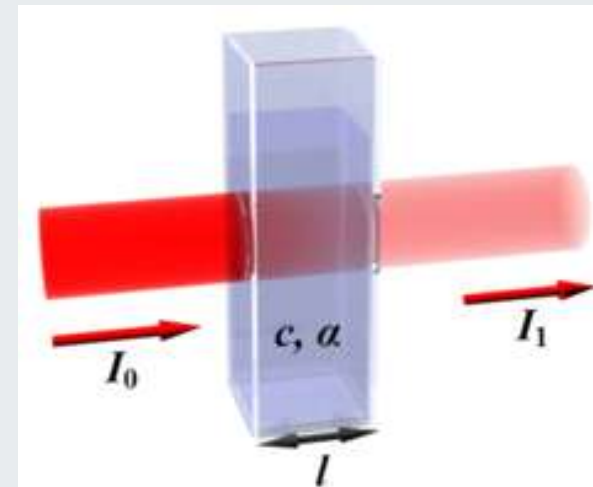
Linear Absorption requires high material absorption coefficient

difficult to achieve if materials transparent

- requires deep UV wavelengths

Beer-Lambert law

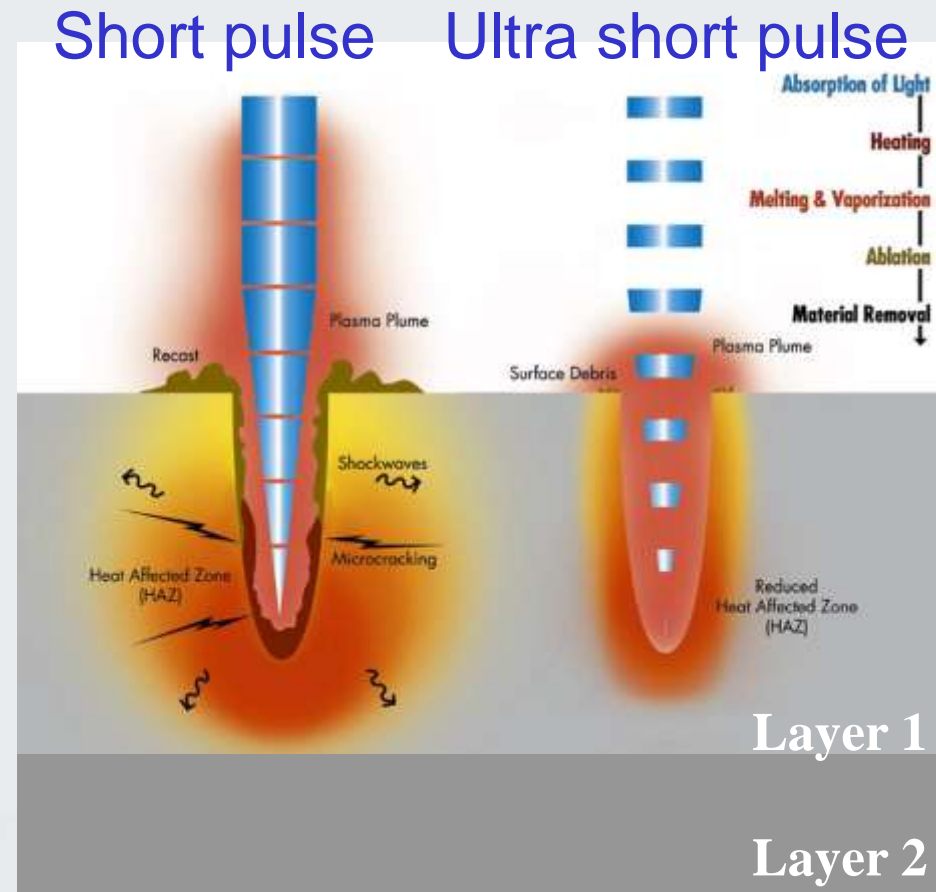
(assuming linear absorption)



Importance of laser pulse duration

- Short pulses (>10ns) associated
 - Thermal ablation processes
 - Prolonged laser+plasma heating
 - Beam attenuation losses
 - Melting and recast debris (evident)
 - Heat affected zone, HAZ (hidden)
 - High removal rates

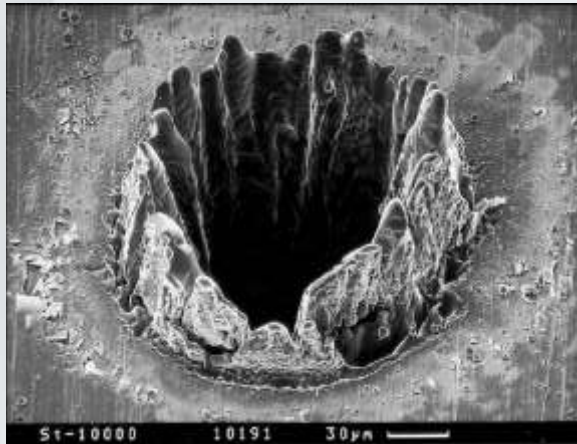
- Ultra short pulses (<0.01ns)
 - “Cold” ablation processes
 - Shorter plasma lifetime
 - Rapid energy deposition (less debris)
 - Deterministic ablation thresholds
 - Restricted HAZ
 - Low removal rate



The laser pulse duration determines the “**heat spreading**” in the material. Crucial for micromachining is minimal thermal damage

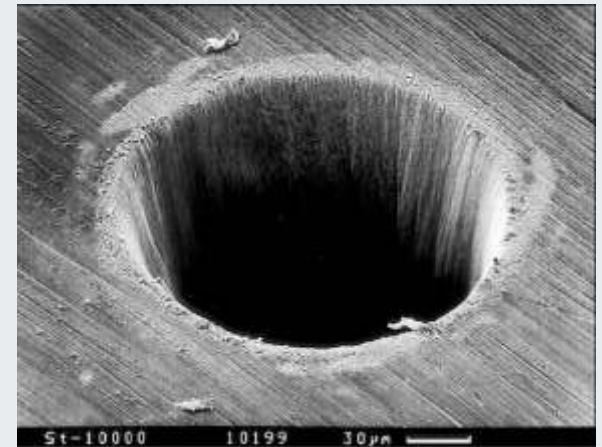
How short is short?

ns pulses



- Melt, burr, HAZ
- Limited accuracy
- High throughput

fs pulses

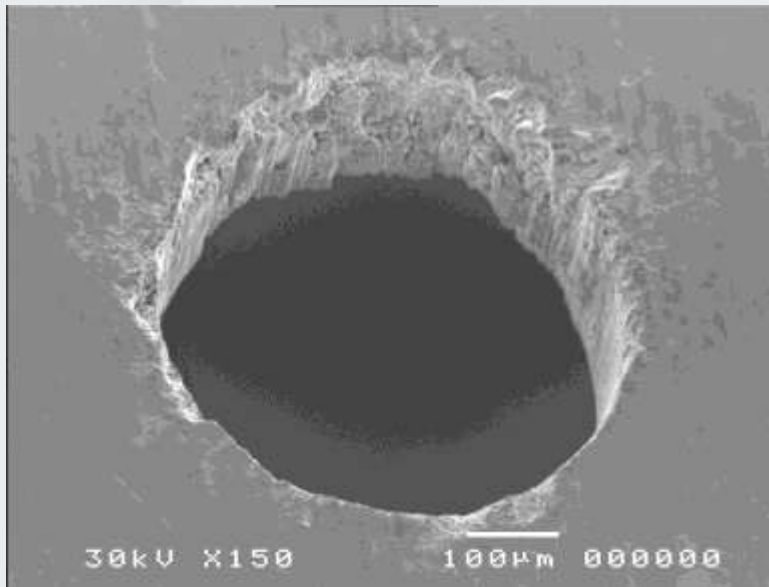


- Perfect quality
- High accuracy
- Slow

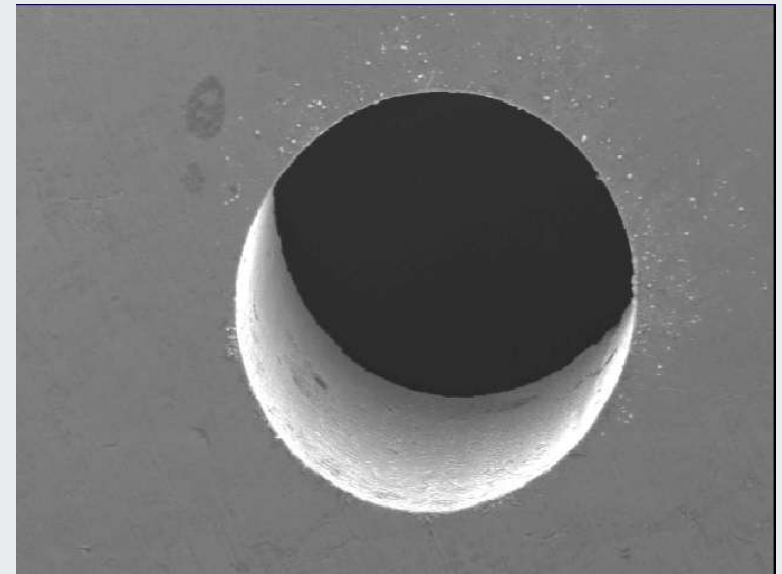
C. Momma, B.N. Chichkov, S. Nolte, F. von Alvensleben, A. Tünnermann, H. Welling, B. Wellegehausen, "Short-pulse laser ablation of solid targets", Opt. Commun. **129**, 134 (1996)



Which one was drilled with a ps laser?



A

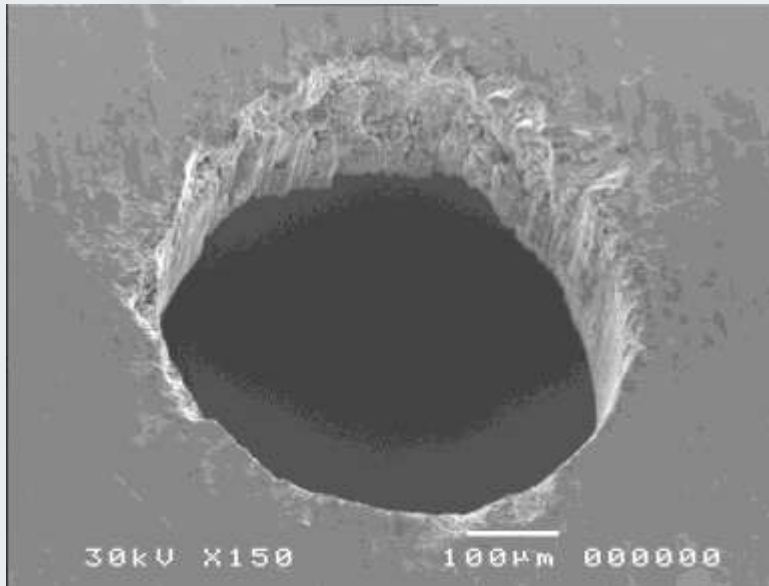


B

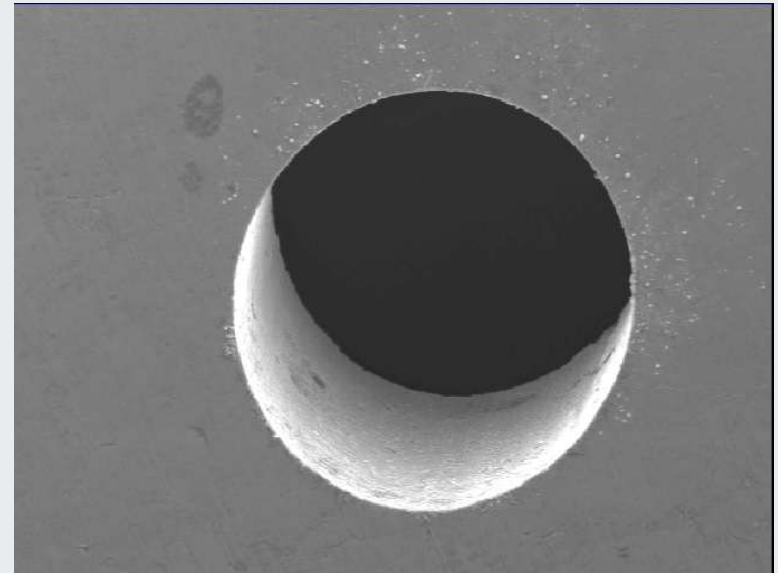
500µm diameter holes drilled in steel:

- one drilled with a nanosecond laser,
- one drilled with a picosecond laser

Answer.....



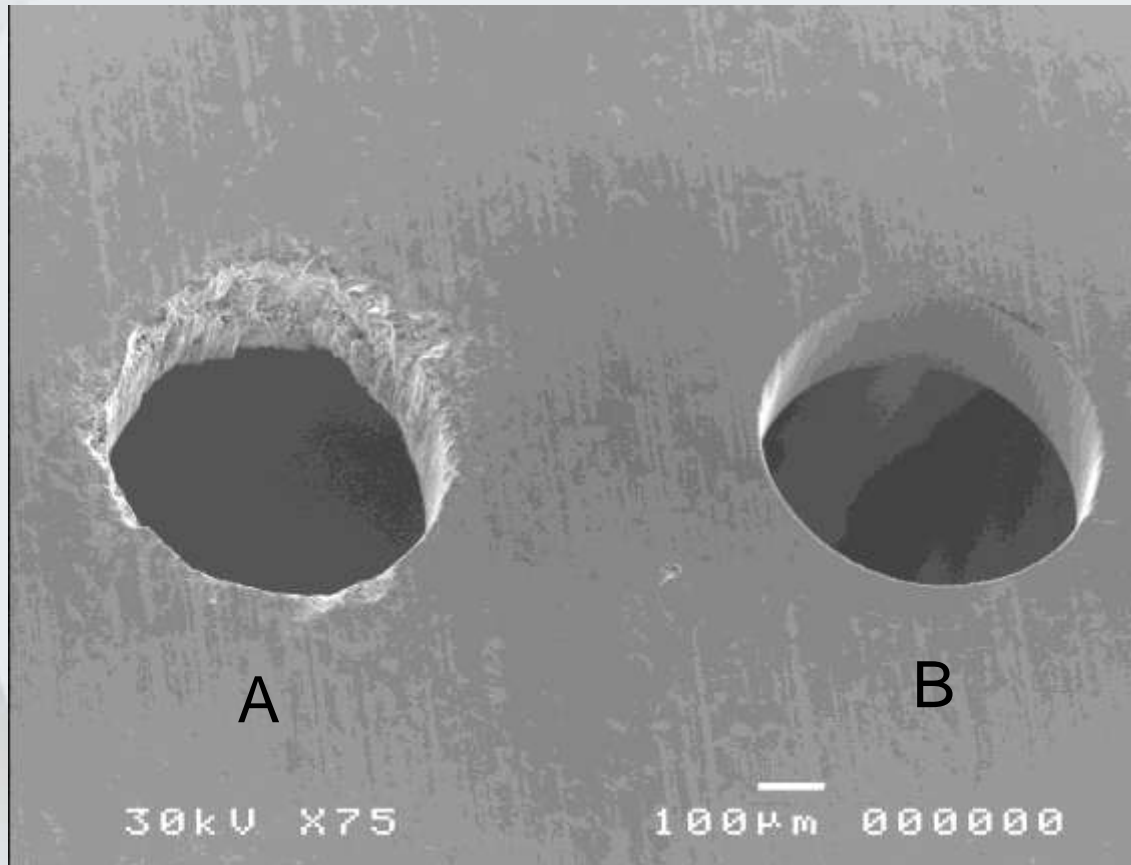
Picosecond



Nanosecond

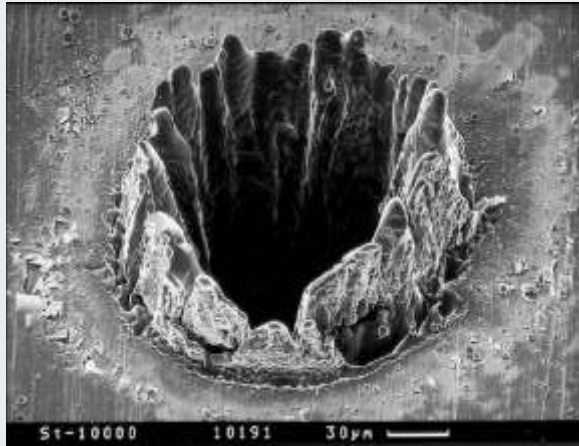
500um diameter hole in steel

Which one was drilled with a Ps laser?

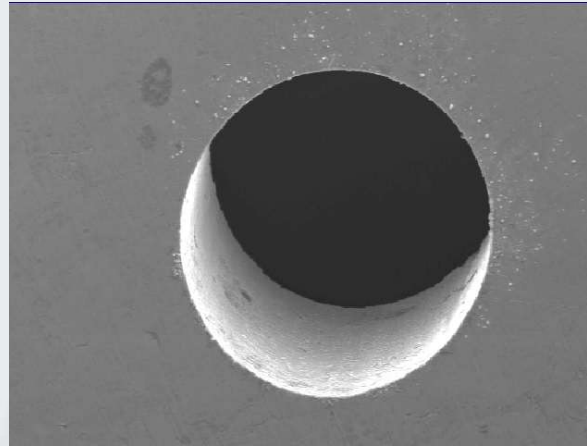


500um hole diameter in Steel

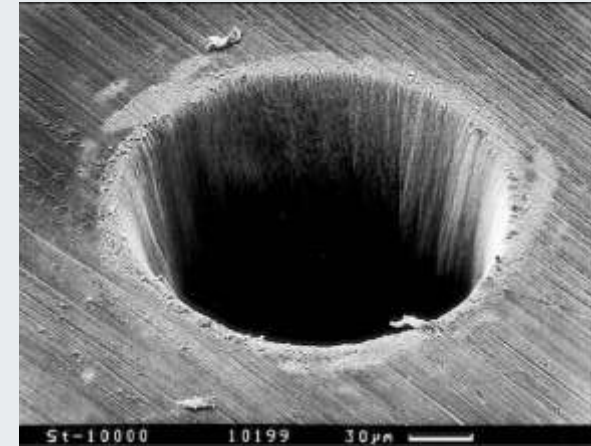
Process first, pulse duration second



Nanosecond



Nanosecond



Femtosecond

- Ultrashort pulse lasers can produce **poor** quality
- Nanosecond lasers can produce **superb** quality
- **Process is key**
- In comparing lasers and sources it is **vital** that processes are optimised

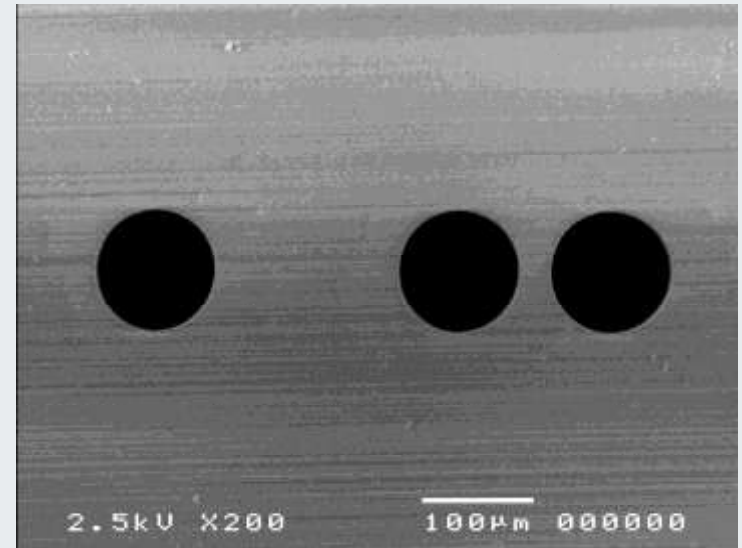
Example 1 - Drilling Silicon Nitride

Task is to drill arrays of holes in Silicon Nitride

Good absorption with green nanosecond light

- Key Components :
- high quality air bearing stages,
 - optical trepan head
 - fast optical attenuator

High quality drilling requires use of optical trepan head

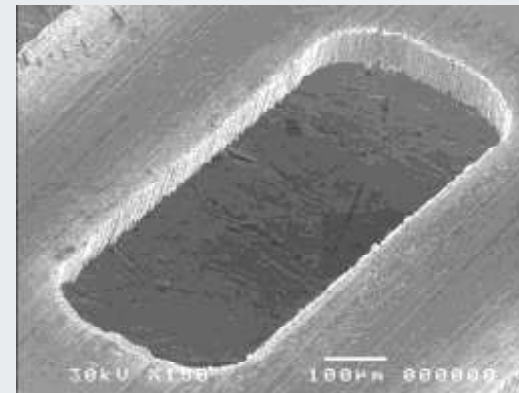
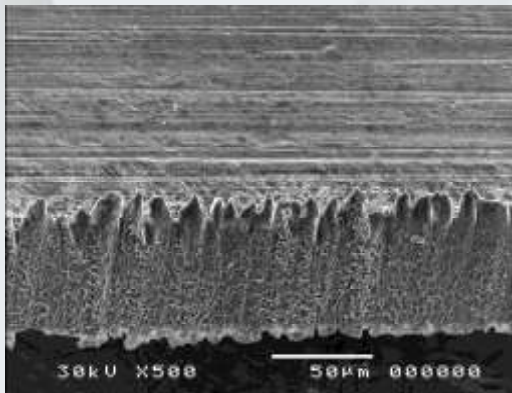


Case Study 2 - Cutting Nickel Foil Electronic Components

Task is to cut a variety of shapes from sheets of Nickel

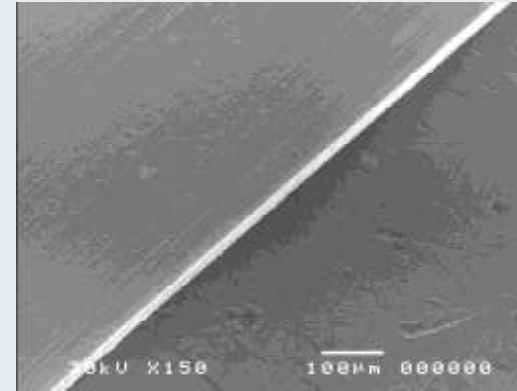
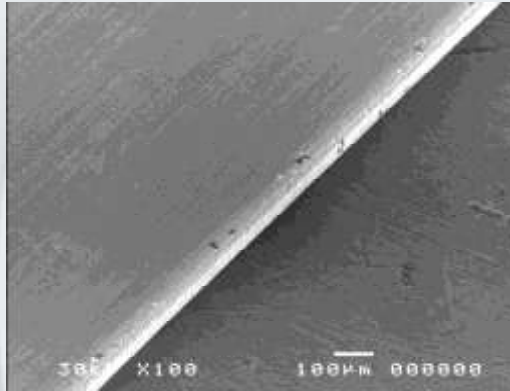
Material shows good absorption with Visible or UV light

Key Components : High quality Galvo Scanner, fast optical attenuator



Nanosecond Processing

Example 2 - Cutting Nickel



Picosecond Processing

Conclusion :

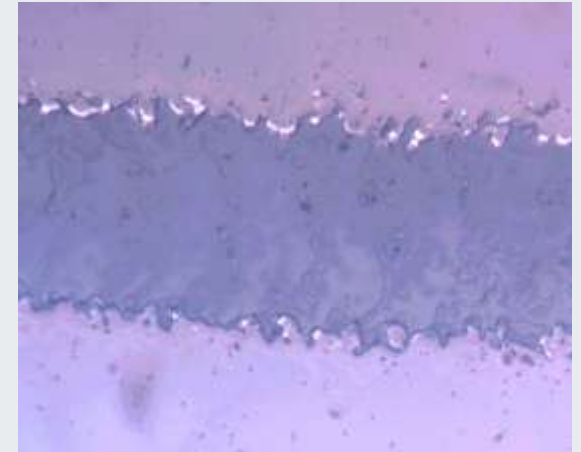
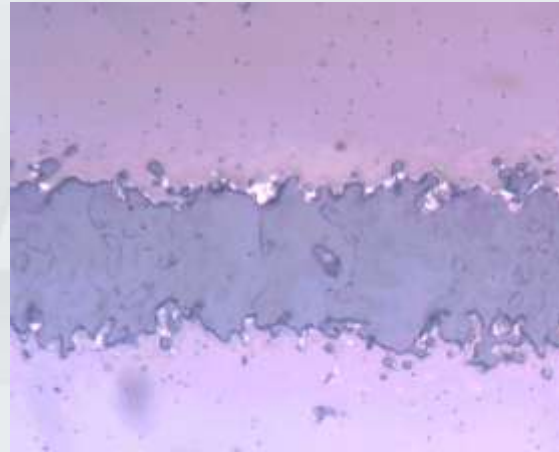
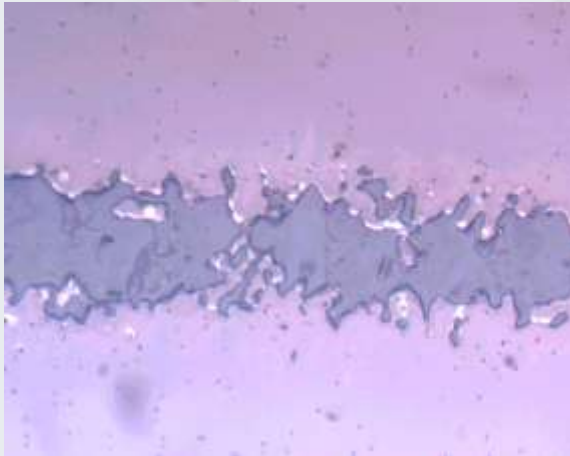
- Pico second laser - pulse duration 10ps
- Wavelength UV - good choice

Example 3 - ITO on polymer

Task is to pattern ITO on polymer film

Material to be removed is only 100nm thick

Key Components : - picosecond laser,
- fast optical attenuator,
- direct writing ?



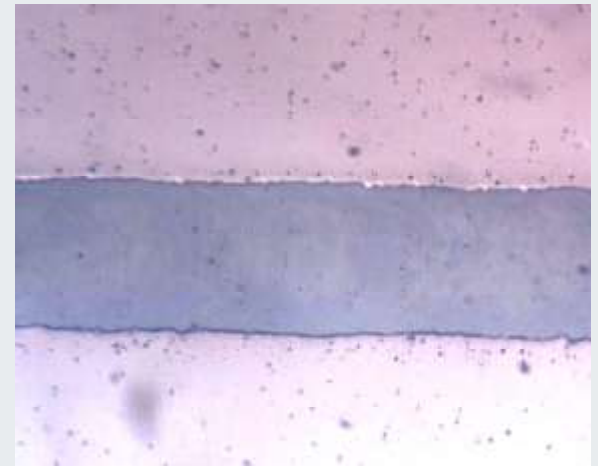
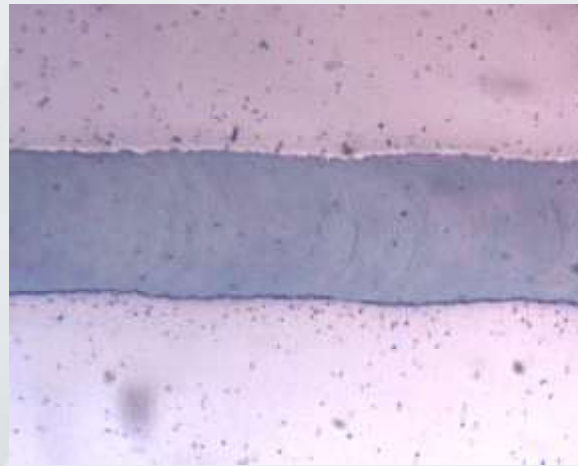
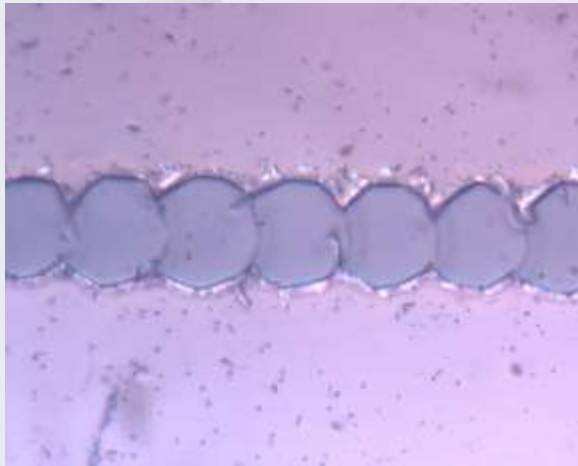
Line (A) : a) low fluence

b) mid range fluence

c) high fluence

Controlling the Process: Thin Film Ablation

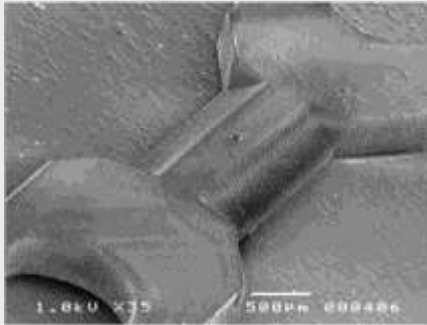
- Key Components :
- picosecond laser,
 - fast optical attenuator,
 - modified optical set-up



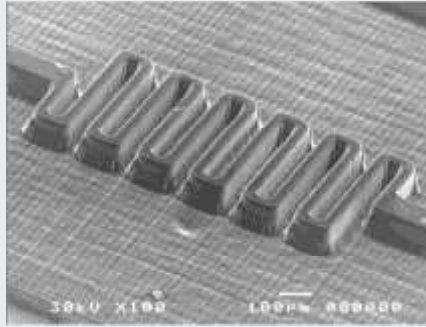
Changed optical set-up, same laser, same low fluence,

Note slight wobble in path: application may need better X,Y stages

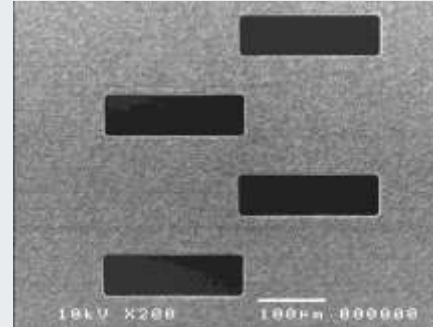
Examples of ns laser machined features



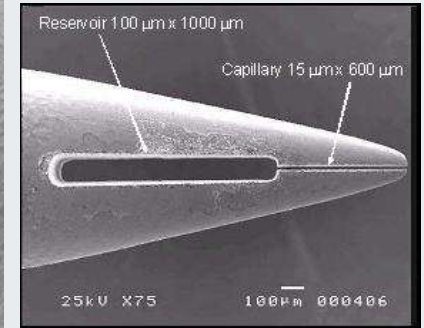
Silicon Nitride



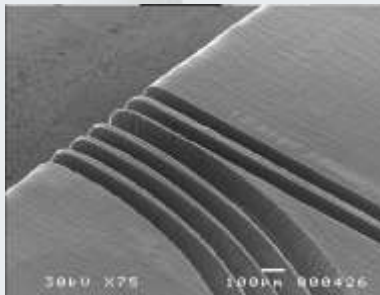
Diamond



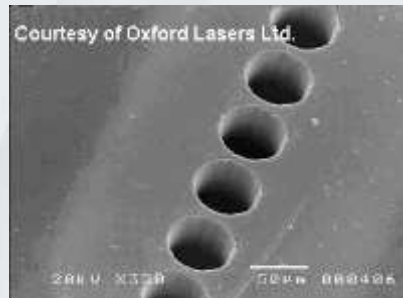
Silicon Nitride



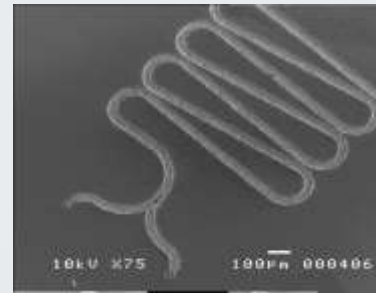
Tungsten



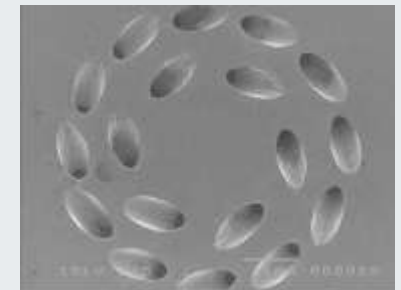
Polyimide



Polyimide

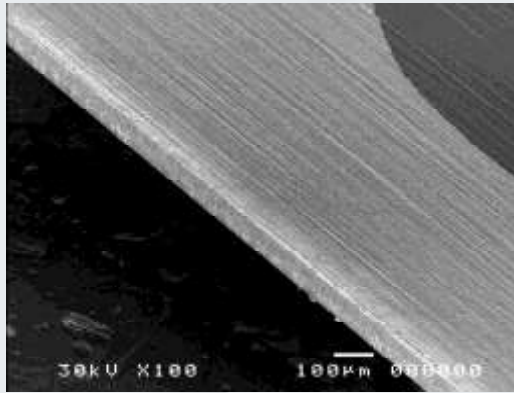


Glass

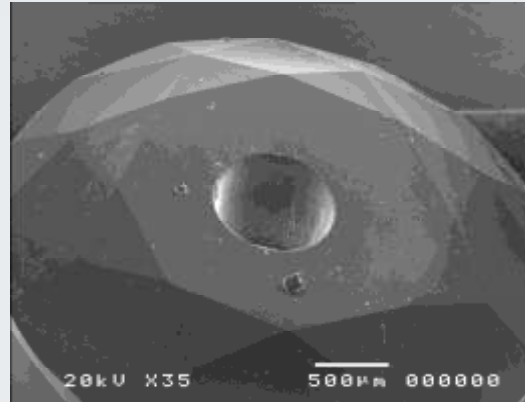


Stainless Steel

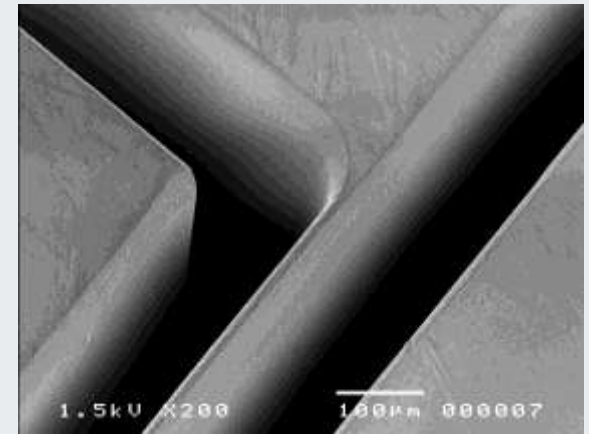
Examples of ps laser machined features



Nickel



**Drilling diamond –
500 micron hole**

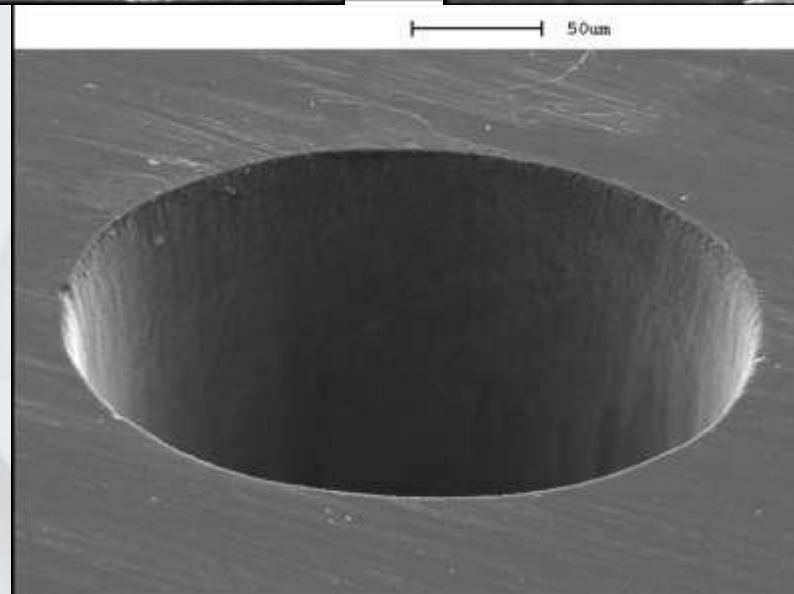
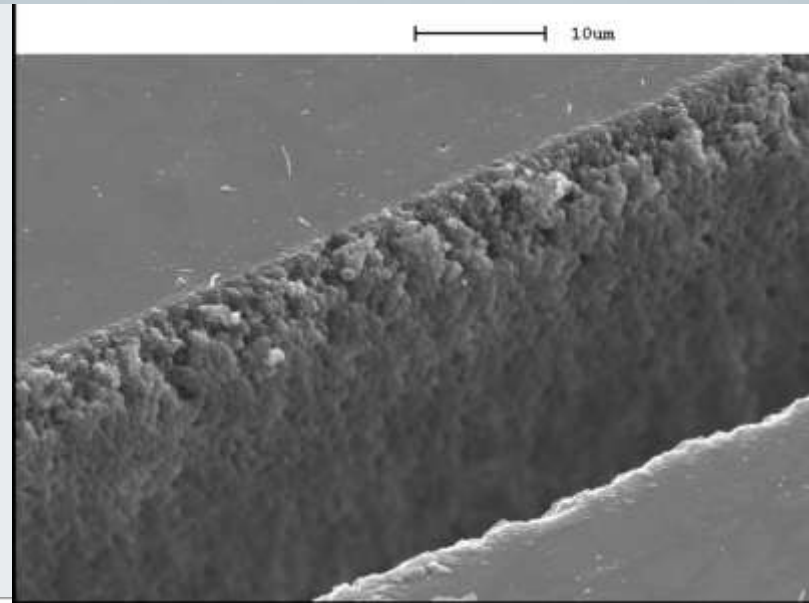
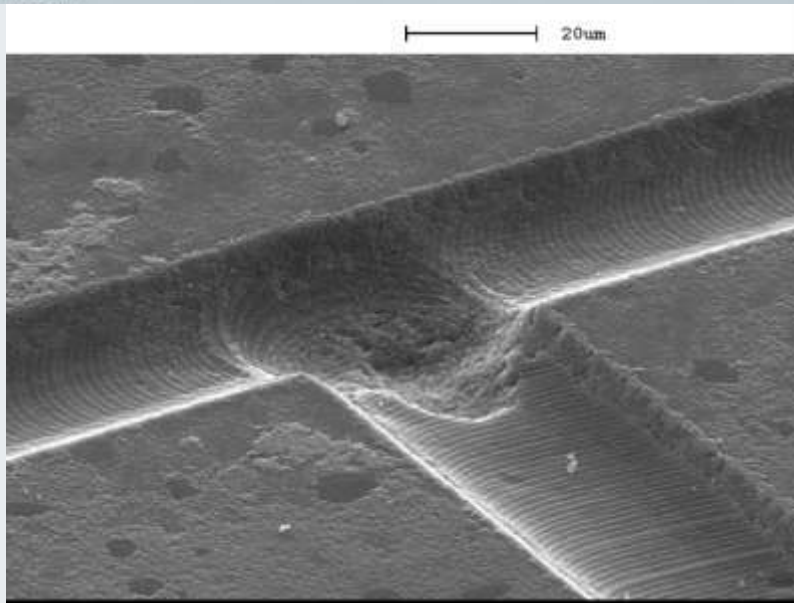


Sapphire cutting



**Patterning -
10 micron wide tracks on 70 micron pitch**

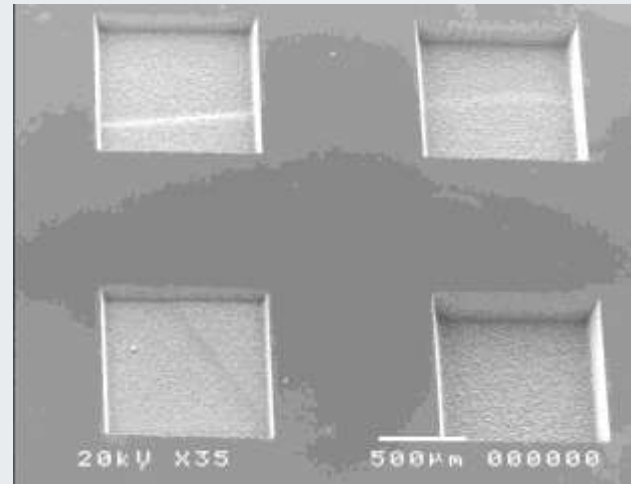
Example 5 : Fs laser Borosilicate



Examples of fs laser machined features



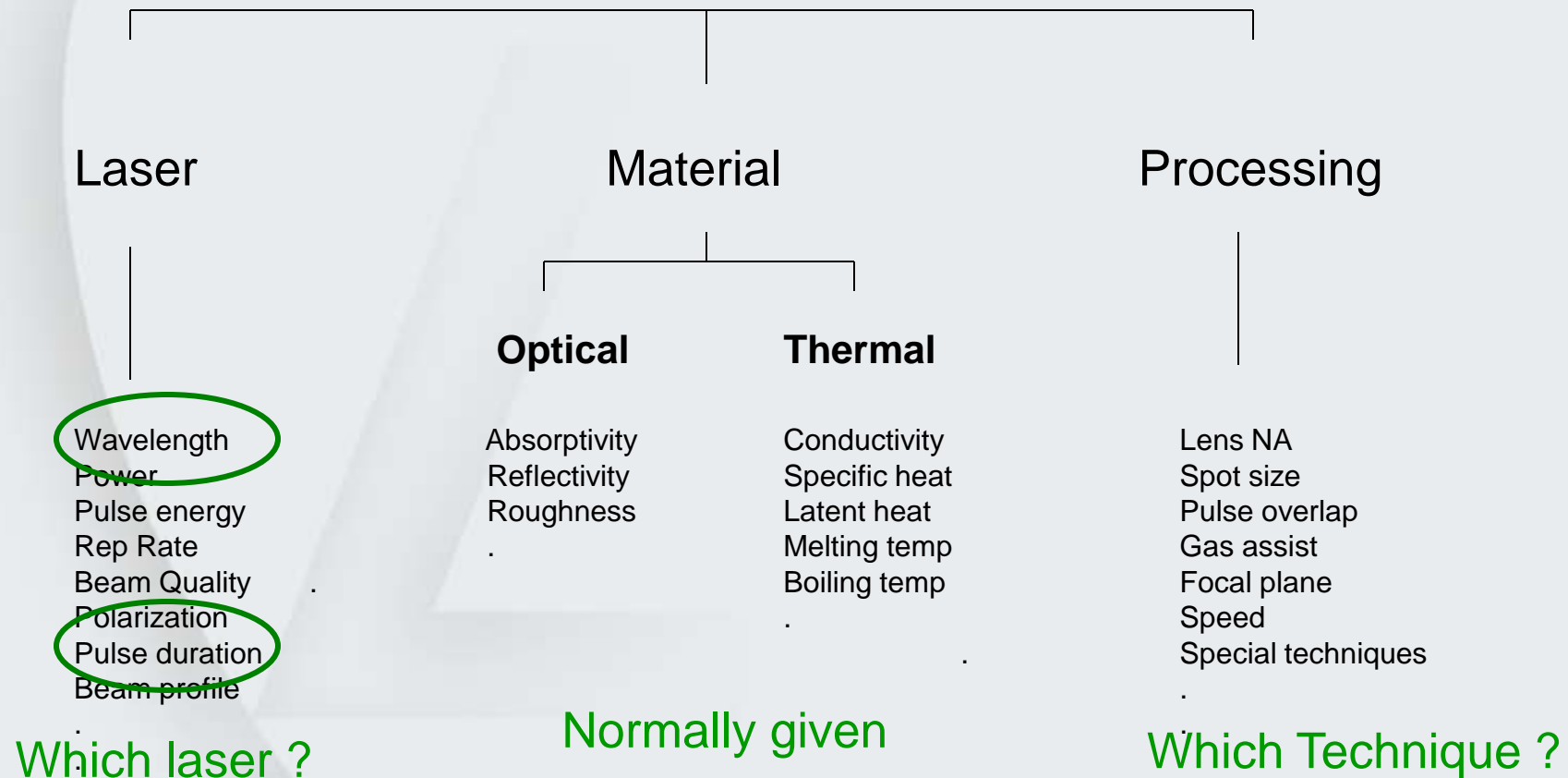
Borosilicate



Glass

Summary

Laser Machining: Important Parameters



! IMPORTANT: Most parameters are interrelated.



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